



Material Content Data Sheet



Sales Product Name	BSC057N08NS3 G			Issued		11. November 2019		
MA#	MA001509956							
Package	PG-TDSON-8-39			Weight*		113.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.666	3.22	3.22	32207	32207
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.048	0.04		425	
	non noble metal	copper	7440-50-8	48.352	42.48	42.53	424759	425312
wire	non noble metal	copper	7440-50-8	0.066	0.06	0.06	576	576
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		696	
	plastics	epoxy resin	-	6.256	5.50		54955	
	inorganic material	silicondioxide	60676-86-0	33.259	29.22	34.79	292164	347815
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13353	13353
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1392	1392
solder	non noble metal	tin	7440-31-5	0.061	0.05		533	
	noble metal	silver	7440-22-4	0.076	0.07		667	
	non noble metal	lead	7439-92-1	2.899	2.55	2.67	25470	26670
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1318	
	non noble metal	copper	7440-50-8	16.910	14.85	14.99	148549	150061
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2610	2614
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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